



Material Content Data Sheet



Sales Product Name	TLE4998P8D			Issued	22. January 2018			
MA#	MA001220392							
Package	PG-TDSO-8-2			Weight*	68.13 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.851	5.65	5.65	56533	56533
leadframe	non noble metal	zinc	7440-66-6	0.064	0.09		945	
	non noble metal	tin	7440-31-5	0.080	0.12		1181	
	non noble metal	chromium	7440-47-3	0.097	0.14		1417	
wire	non noble metal	copper	7440-50-8	31.938	46.89	47.24	468795	472338
	noble metal	gold	7440-57-5	0.118	0.17	0.17	1733	1733
	encapsulation	organic material	carbon black	1333-86-4	0.060	0.09		882
glue	plastics	epoxy resin	-	3.244	4.76		47619	
	inorganic material	silicondioxide	60676-86-0	26.735	39.24	44.09	392420	440921
	leadfinish	non noble metal	tin	7440-31-5	0.497	0.73	0.73	7298
plating	noble metal	silver	7440-22-4	0.953	1.40	1.40	13982	13982
glue	plastics	epoxy resin	-	0.123	0.18		1799	
	plastics	acrylic resin	-	0.123	0.18		1799	
	inorganic material	silicondioxide	60676-86-0	0.245	0.36	0.72	3597	7195
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com